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***Substitute Specification***

**Application No. 09/986,302**

**SCANNING EXPOSURE APPARATUS AND  
DEVICE MANUFACTURING METHOD USING THE SAME**

**FIELD OF THE INVENTION AND RELATED ART**

This invention relates to a scanning exposure apparatus and a device manufacturing method using the same. More particularly, the invention concerns a scanning exposure apparatus and a device manufacturing method which are suitably usable in a projection exposure step in a photolithographic process for transferring a pattern of a reticle onto a photosensitive substrate by use of a continuous emission excimer laser, which may be used as a light source. Here, the photolithographic process is a process specifically for the manufacture of semiconductor devices such as ICs or LSIs, image pickup devices such as CCDs, display devices such as liquid crystal panels, and magnetic head devices, for example.

In an illumination optical system usable in an exposure apparatus for the manufacture of semiconductor devices, light from a light source may be scanningly deflected by a scanning system to produce a secondary light source, by which a surface to be illuminated, such as a reticle, can be illuminated with light from the secondary light source (Japanese Laid-Open Patent Application, Laid-Open No. 163547/1998).

Scan type projection exposure apparatuses are arranged so that a reticle and a wafer are scanned thereby to transfer a pattern of the reticle onto the wafer, and they have a feature